

Property Economics

System LED Drivers for Mobile phones



BD2802GU

No.11041EAT12

Description

The BD2802GU is a RGB LED driver specifically engineered for decoration purposes. This RGB driver incorporates lighting patterns and illuminates without imposing any load on CPU. This RGB driver is best-suited for illumination using RGB LEDs and decoration using monochrome LEDs. In addition, this RGB driver has been successfully miniaturized through the use of a VCSP85H2 (2.8 mm 0.5 mm pitch) chip size package.

Features

- 1) RGB LED driver (dual drivers)
 - A slope control function is incorporated (allowing dual drivers to be controlled independently).
 - Slope control can be implemented using the DC current.
 - Two modes "continuous illumination mode" and "illumination single cycle mode" are supported.
 - Independent external ON/OFF synchronizing terminals (of dual drivers) are provided.
 - Multiple drivers can be used concurrently by using the I²C address change function and supporting reference clock I/O.
- 2) Thermal shutdown
- 3) I²C BUS fast mode support (maximum rate: 400 kHz)
 - A device address can be changed via an external pin.
- * This driver has not been designed for anti-radiation.
- This document may be altered without prior notice.
- * This document does not provide for delivery.

●Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Limits	Unit
Maximum Applied voltage	VMAX	7	V
Power Dissipation	Pd	1250 ^(Note1)	mW
Operating Temperature Range	Topr	-40 ~ +85	°C
Storage Temperature Range	Tstg	-55 ~ +150	°C

(Note1)Power dissipation deleting is 10.0mW/ $^{\circ}$ C, when it's used in over 25 $^{\circ}$ C. (It's deleting is on the board that is ROHM's standard)

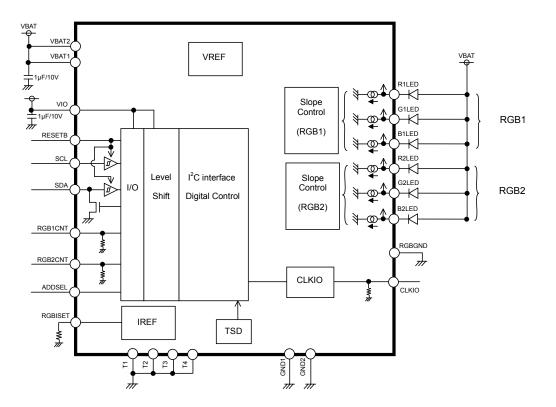
●Recommended Operating Conditions(VBAT≧VIO, Ta=-40~85°C)

Parameter	Symbol	Limits	Unit
VBAT input voltage	VBAT	2.7 ~ 5.5	V
VIO pin voltage	VIO	1.65 ~ 3.3	V

●Electrical Characteristics(Unless otherwise specified, Ta=25°C, VBAT=3.6V, VIO=1.8V)

				VDA1-0.0V	, 10-1.	
Parameter	Symbol	Min.	Limits Typ.	Max.	Unit	Condition
[Circuit Current]			51			
VBAT Circuit current 1	IBAT1	_	0.1	3.0	μA	RESETB=0V, VIO =0V
VBAT Circuit current 2	IBAT2	_	0.5	3.0	μA	RESETB=0V, VIO=1.8V
VBAT Circuit current 3	IBAT3	-	0.8	1.2	mA	LED 6Ch ON, ILED=10mA setting Exclusive of LED current, RGBISET =120k Ω
[LED Driver]						
LED current Step	ILEDSTP		128		step	RGB1 group, RGB2 group
LED Maximum setup curren	IMAX	-	-	30.48	mA	RGB1 group, RGB2 group RGBISET=100kΩ
LED current accurate	ILED	18	20	22	mA	RGB1 group, RGB2 group, Terminal voltage =1V ILED=20mA setting, RGBISET =120kΩ
LED current Matching	ILEDMT	-	5	10	%	RGB1 group, between RGB2 group, Terminal voltage =1V ILED=20mA setting
LED OFF Leak current	ILKL	-	-	1.0	μA	
[OSC]						
OSC oscillation frequency	fosc	0.8	1.0	1.2	MHz	
[SDA, SCL] (I2C interfac	e)					
L level input voltage	VILI	-0.3	-	0.25×VIO	V	
H level input voltage	VIHI	0.75×VIO	-	VBAT+0.3	V	
Hysteresis of Schmitt trigger input	Vhysl	0.05×VIO	-	-	V	
L level output voltage	VOLI	0	-	0.3	V	SDA pin, IOL=3 mA
Input current	linl	-10	-	10	μA	Input voltage = 0.1×VIO~0.9×VIO
【RESETB】(CMOS input	pin)	1	1	1		L
L level input voltage	VILR	-0.3	-	0.25×VIO	V	
H level input voltage	VIHR	0.75×VIO	-	VBAT+0.3	V	
Input current	linR	-10	-	10	μA	Input voltage = 0.1×VIO~0.9×VIO
[ADDSEL] (CMOS input	pin)				•	
L level input voltage	VILADD	-0.3	-	0.25×VBAT	V	
H level input voltage		0.7 ×VBAT	_	VBAT+0.3	V	
Input current	linADD	-10	_	10	μA	Input voltage = 0.1×VBAT~0.9×VBAT
[RGB1CNT, RGB2CNT]			Pull-down r		Pr. 1	
L level input voltage	VILCNT	-0.3	-	0.25×VIO	V	
H level input voltage	VIECINT	0.75×VIO	_	VBAT+0.3	V	
Input current	linCNT	-	3.6	10	μA	Input voltage = 1.8V
[CLKIO(Output)] (CMOS		<u> </u>	0.0	10	μ, ,	
L level output voltage	VOLCLK	-	_	0.2	V	IOL=1mA
H level output voltage	VOLCLK	- VIO-0.2	_	0.2	V	IOL-IMA IOH=1mA
Output frequency	fclk	200	- 250	300		
[CLKIO (Input)] (CMOS		200	200	300	kHz	
		0.0		0.05-0/10	11	
L level input voltage	VILCLK	-0.3	-	0.25×VIO	V	
H level input voltage	VIHCLK	0.75×VIO	-	VIO+0.3	V	
Input current	linCLK	-	3.6	10	μA	Input voltage = 1.8V

Block Diagram / Application Circuit example



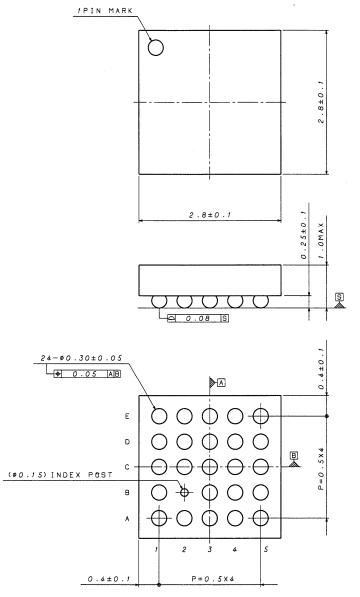


•Pin Arrangement [Bottom View]

E	T4	G2LED	RGBGND	G1LED	Т3
D	B2LED	R2LED	B1LED	R1LED	VBAT1
С	VBAT2	RGBISE	RGB1CNT	ADDSEL	GND2
В	GND1	index	CLKIO	SCL	SDA
A	T1	RGB2CNT	VIO	RESETB	T2
	1	2	3	4	5

Outside size figure

VCSP85H2 CSP small Package Size : 2.8mm×2.8mm (Tolerance : ± 0.1mm each side) height 1.0mm max Ball pitch : 0.5 mm



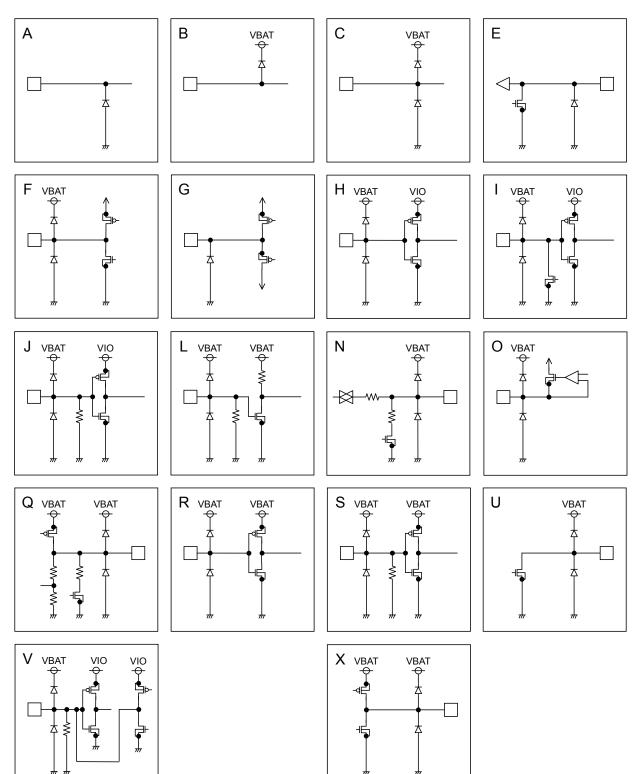
(UNIT:mm)

Pin Functions

No	Pin No.	Pin Name	I/O	Input For Power	Level For GND	ESD Diode	Functions
1	D5	VBAT1	-	-	GND	Battery is connected	А
2	C1	VBAT2	-	-	GND	Battery is connected	А
3	A1	T1	-	VBAT	GND	Test Pin (short to GND)	S
4	A5	T2	-	VBAT	GND	Test Pin (short to GND)	S
5	E5	Т3	-	VBAT	GND	Test Pin (short to GND)	S
6	E1	T4	-	VBAT	-	Test Pin (short to GND)	В
7	A3	VIO	-	VBAT	GND	I/O voltage source is connected	С
8	A4	RESETB	I	VBAT	GND	Reset input (L: RESET, H: RESET cancel)	Н
9	B5	SDA	I/O	VBAT	GND	l ² C data input	I
10	B4	SCL	I	VBAT	GND	I ² C clock input	Н
11	B1	GND1	-	VBAT	-	Ground	В
12	C5	GND2	-	VBAT	-	Ground	В
13	E3	RGBGND	-	VBAT	-	Ground	В
14	C2	RGBISET	I	VBAT	GND	RGB LED reference current	0
15	D4	R1LED	I	-	GND	Red LED1 connected	E
16	E4	G1LED	I	-	GND	Green LED1 connected	E
17	D3	B1LED	I	-	GND	Blue LED1 connected	E
18	D2	R2LED	I	-	GND	Red LED2 connected	E
19	E2	G2LED	I	-	GND	Green LED2 connected	E
20	D1	B2LED	I	-	GND	Blue LED2 connected	E
21	C3	RGB1CNT	I	VBAT	GND	RGB1 LED external ON/OFF Synchronism (L: OFF, H: ON)*	J
22	A2	RGB2CNT	l	VBAT	GND	RGB2 LED external ON/OFF Synchronism (L : OFF, H : ON)*	J
23	C4	ADDSEL	I	VBAT	GND	I ² C device address change terminal	R
24	B3	CLKIO	I/O	VBAT	GND	Standard clock input-and-output terminal	V

* A setup of a register is separately necessary to validate it.

Equivalent circuit diagram



●I²C BUS format

The writing operation is based on the I²C slave standard.

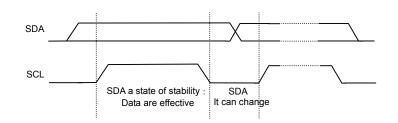
Slave address

-												
		A7	A6	A5	A4	A3	A2	A1	R/W			
	ADDSEL=L	0	0	1	1	0	1	0	0			
	ADDSEL=H	0	0	1	1	0	1	1	0			

Slave address can be changed with the external terminal ADDSEL.

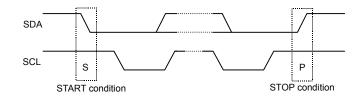
Bit Transfer

SCL transfers 1-bit data during H. SCL cannot change signal of SDA during H at the time of bit transfer. If SDA changes while SCL is H, START conditions or STOP conditions will occur and it will be interpreted as a control signal.



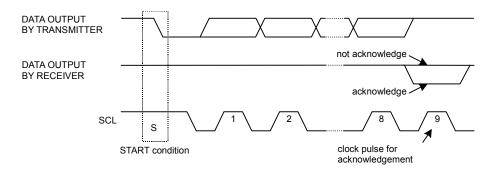
START and STOP condition

When SDA and SCL are H, data is not transferred on the I^2 C- bus. This condition indicates, if SDA changes from H to L while SCL has been H, it will become START (S) conditions, and an access start, if SDA changes from L to H while SCL has been H, it will become STOP (P) conditions and an access end.



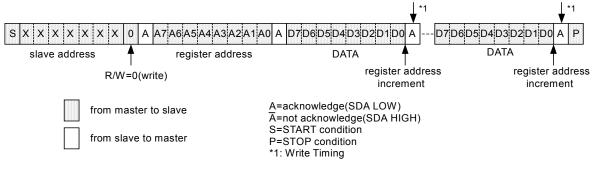
Acknowledge

It transfers data 8 bits each after the occurrence of START condition. A transmitter opens SDA after transfer 8bits data, and a receiver returns the acknowledge signal by setting SDA to L.

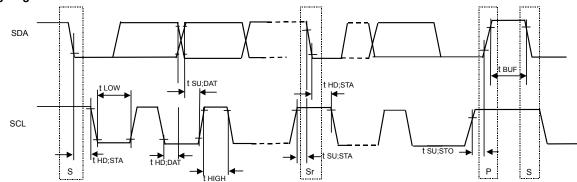


Writing protocol

A register address is transferred by the next 1 byte that transferred the slave address and the write-in command. The 3rd byte writes data in the internal register written in by the 2nd byte, and after 4th byte or, the increment of register address is carried out automatically. However, when a register address turns into the last address, it is set to 00h by the next transmission. After the transmission end, the increment of the address is carried out.



Timing diagram



•Electrical Characteristics(Unless otherwise specified, Ta=25 °C, VBAT=3.6V, VIO=1.8V)

Parameter	Symbol	Sta	andard-m	ode	F	ast-mode		Unit
Parameter	Symbol	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
[I ² C BUS format]								
SCL clock frequency	f SCL	0	-	100	0	-	400	kHz
LOW period of the SCL clock	t∟ow	4.7	-	-	1.3	-	-	μs
HIGH period of the SCL clock	thigh	4.0	-	-	0.6	-	-	μs
Hold time (repeated) START condition	tup ota	4.0			0.6	-	-	
After this period, the first clock is generated	thd;sta	4.0	-	-	0.0			μs
Set-up time for a repeated START	tsu;sta 4	4.7			0.6	-	-	110
condition		4.7	-	-	0.0			μs
Data hold time	thd;dat	0	-	3.45	0	-	0.9	μs
Data set-up time	tsu;dat	250	-	-	100	-	-	ns
Set-up time for STOP condition	tsu;sto	4.0	-	-	0.6	-	-	μs
Bus free time between a STOP	1	47			4.0			
and START condition	tBUF	4.7	-	-	1.3	-	-	μs

Address	W/R				Resiste	er data				Function	
Address	W/K	D7	D6	D5	D4	D3	D2	D1	D0	T UNCLOIT	
00h	W	-	-	CLKMD	CLKEN	-	-	-	SFTRST	Soft Reset clock setup	
01h	W	-	RGB2MEL	RGB2OS	RGB2EN	-	RGB1MEL	RGB10S	RGB1EN	RBG-LED control	
02h	W	SFRGB1(1)	SFRGB1(0)	SRRGB1(1)	SRRGB1(0)	-	TRGB1(2)	TRGB1(1)	TRGB1(0)	RGB1-hour setup	
03h	W	-	IR11(6)	IR11(5)	IR11(4)	IR11(3)	IR11(2)	IR11(1)	IR11(0)	R1 current 1 setup	
04h	W	-	IR12(6)	IR12(5)	IR12(4)	IR12(3)	IR12(2)	IR12(1)	IR12(0)	R1 current 2 setup	
05h	W	-	-	-	-	PR1(3)	PR1(2)	PR1(1)	PR1(0)	R1 Wave patturn setup	
06h	W	-	IG11(6)	IG11(5)	IG11(4)	IG11(3)	IG11(2)	IG11(1)	IG11(0)	G1 current 1 setup	
07h	W	-	IG12(6)	IG12(5)	IG12(4)	IG12(3)	IG12(2)	IG12(1)	IG12(0)	G1 current 2 setup	
08h	W	-	-	-	-	PG1(3)	PG1(2)	PG1(1)	PG1(0)	G1 Wave patturn setup	
09h	W	-	IB11(6)	IB11(5)	IB11(4)	IB11(3)	IB11(2)	IB11(1)	IB11(0)	B1 current 1 setup	
0Ah	W	-	IB12(6)	IB12(5)	IB12(4)	IB12(3)	IB12(2)	IB12(1)	IB12(0)	B1 current 2 setup	
0Bh	W	-	-	-	-	PB1(3)	PB1(2)	PB1(1)	PB1(0)	B1 Wave patturn setup	
0Ch	W	SFRGB2(1)	SFRGB2(0)	SRRGB2(1)	SRRGB2(0)	-	TRGB2(2)	TRGB2(1)	TRGB2(0)	RGB2-hour setup	
0Dh	W	-	IR21(6)	IR21(5)	IR21(4)	IR21(3)	IR21(2)	IR21(1)	IR21(0)	R2 current 1 setup	
0Eh	W	-	IR22(6)	IR22(5)	IR22(4)	IR22(3)	IR22(2)	IR22(1)	IR22(0)	R2 current 2 setup	
0Fh	W	-	-	-	-	PR2(3)	PR2(2)	PR2(1)	PR2(0)	R2 Wave patturn	
10h	W	-	IG21(6)	IG21(5)	IG21(4)	IG21(3)	IG21(2)	IG21(1)	IG21(0)	G2 current 1 setup	
11h	W	-	IG22(6)	IG22(5)	IG22(4)	IG22(3)	IG22(2)	IG22(1)	IG22(0)	G2 current 2 setup	
12h	W	-	-	-	-	PG2(3)	PG2(2)	PG2(1)	PG2(0)	G2 Wave patturn setup	
13h	W	-	IB21(6)	IB21(5)	IB21(4)	IB21(3)	IB21(2)	IB21(1)	IB21(0)	B2 current 1 setup	
14h	W	-	IB22(6)	IB22(5)	IB22(4)	IB22(3)	IB22(2)	IB22(1)	IB22(0)	B2 current 2 setup	
15h	W	-	-	-	-	PB2(3)	PB2(2)	PB2(1)	PB2(0)	B2 Wave patturn setup	

Register map

Input "0" for "-".

Vacancy address may be use for test. Prohibit to accessing the address that isn't mentioned and the register for test.

Register Description

Adress 00h <Soft Reset>

BIT	Name	Initial	Fun	Function		
DII	Name	IIIIIdi	0	1		
D7	-	-	-	-		
D6	-	-	-	-		
D5	CLKMD	0	Clock Input mode	Clock Output mode		
D4	CLKEN	0	Clock input and output invalid	Clock input and output Effective		
D3	-	-	-	-		
D2	-	-	-	-		
D1	-	-	-	-		
D0	SFTRST	0	Reset Release	Reset		

Adress 01h <RGB LED control >

BIT	Name	Name	Init	Fund	ction
DII	Name	Init	0	1	
D7	-	-	-	-	
D6	RGB2MEL	0	RGB2 external control invalid	RGB2 external control valid	
D5	RGB2OS	0	RGB2 Stop	RGB2 1 periodic operation	
D4	RGB2EN	0	RGB2 Stop	RGB2 continuous operation	
D3	-	-	-	-	
D2	RGB1MEL	0	RGB1 external control invalid	RGB1 external control valid	
D1	RGB10S	0	RGB1 Stop	RGB1 1 periodic operation	
D0	RGB1EN	0	RGB1 Stop	RGB1 continuous operation	

* RGB*OS returns to 0 automatically after 1 cycle operation.

* RGB*EN precedes to RGB*OS. In use in 1 cycle operation, there is the necessity for RGB*EN=0.

Name							
	Init			Function			
Name	mmt		0		1		
		SFRGB1(1)	SFRGB1(0)	Slope Down transition		
SFRGB1(1)	0	0		0	0		
		0		1	Wave form cycle / 16		
		1		0	Wave form cycle / 8		
		1		1	Wave form cycle / 4		
SFRGB1(0)	0						
				SRRGB1(1)	SRRGB1(0)	Slope Up transition
SRRGB1(1)	0	0	/	0	0		
		0		1	Wave form cycle / 16		
		1		0	Wave form cycle / 8		
	RGB1(0) 0	1		1	Wave form cycle / 4		
SRRGB1(0)							
-	-		-		-		
		TRGB1(2)	TRGB1(1)	TRGB1(0)	Wave form cycle		
TRGB1(2)	0	0	0	0	0.131 s		
		0	0	1	0.52 s		
		0	1	0	1.05 s		
TRGB1(1)	0	0	1	1	2.10 s		
		1	0	0	4.19 s		
		1	0	1	8.39 s		
	0	1	1	0	12.6 s		
		1	1	1	16.8 s		
	SFRGB1(0) SRRGB1(1) SRRGB1(0) - TRGB1(2)	SFRGB1(0) 0 SRRGB1(1) 0 SRRGB1(0) 0	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	SFRGB1(0) 0 1 SFRGB1(0) 0 1 1 SRRGB1(1) 0 1 1 SRRGB1(1) 0 0 0 SRRGB1(1) 0 0 0 SRRGB1(0) 0 1 1 SRRGB1(0) 0 1 1 SRRGB1(0) 0 1 1 TRGB1(2) 0 1 1 TRGB1(2) 0 1 1 TRGB1(1) 0 0 1 TRGB1(1) 0 1 0 TRGB1(1) 0 1 0 TRGB1(1) 0 1 0	SFRGB1(1) 0 0 0 0 0 1 0 0 1 0 1 SFRGB1(0) 0 1 1 SFRGB1(0) 0 1 1 SRRGB1(1) 0 SRRGB1(1) SRRGB1(0) SRRGB1(1) 0 1 1 SRRGB1(0) 0 1 1 SRRGB1(0) 0 1 1 SRRGB1(0) 0 1 1 TRGB1(2) 0 1 1 TRGB1(2) 0 1 1 TRGB1(1) 0 1 0 TRGB1(1) 0 1 0 TRGB1(1) 0 1 0 TRGB1(1) 0 1 1 1 0 1 1 1 0 1 1		

Setting time is counted based on the frequency of OSC. The above-mentioned value is a value at the time of Typ (1MHz). When operating by the external clock, input frequency is a value at the time of Typ (250kHz).

Adress 03h <R1 current 1setup >

BIT	Name	Init				Fur	nction				
DII	name	IIIIL		0				1			
D7	-	-		-				-			
D6	IR11(6)	0	IR11(6)	IR11(5)	IR11(4)	IR11(3)	IR11(2)	IR11(1)	IR11(0)	Current	
D5	IR11(5)	0	0	0	0	0	0	0	0	0	
D4	IR11(4)	0	0	0	0	0	0	0	1	0.2mA	
D3	IR11(3)	0			•	•		•	•	0.2mA step	
D2	IR11(2)	0	1	1	1	1	1	1	0	25.2mA	
D1	IR11(1)	0	1	1	1	1	1	1	1	25.4mA	
D0	IR11(0)	0	At RGBISE	Tpin 120k	Ω connect	ion					

Adress 04h <R1 current2 setup >

BIT	Name	Init				Fun	iction		Function							
DII	Name	IIIIL		0				1								
D7	-	-		-					-							
D6	IR12(6)	0	IR12(6)	IR12(5)	IR12(4)	IR12(3)	IR12(2)	IR12(1)	IR12(0)	Current						
D5	IR12(5)	0	0	0	0	0	0	0	0	0						
D4	IR12(4)	0	0	0	0	0	0	0	1	0.2mA						
D3	IR12(3)	0	•	•	•	•	•	•	•	0.2mA						
D2	IR12(2)	0	1	•	•	•	•	•		step 25.2mA						
D1	IR12(1)	0	1	1	1	1	1	1	1	25.2mA 25.4mA						
D0	IR12(0)	0	At RGBISETpin 120kΩ connection													

Adress 05h <R1 Wave Pattern >

BIT	Name	Init			Fu	nction			
DII	Name	IIIIC		0			1		
D7	-	-		-		-			
D6	-	-		-			-		
D5	-	-		-			-		
D4	-	-		-			-		
D3	PR1(3)	0	PR1(3)	PR1(2)	PR1(1)	PR1(0)	Wave		
00	11(1(0)	0	0	0	0	0	Pattern1		
			0	0	0	1	Pattern2		
D2	PR1(2)	1	0	0	1	0	Pattern3		
			•	•	•	•	•		
			•	•	-	•	•		
D1	PR1(1)	1	•	•	•	•	•		
			1	1	0	1	Pattern14		
50			1	1	1	0	Pattern15		
D0	00 PR1(0)		PR1(0) 1		1	1	1	1	Pattern16

Adress 06h <G1 current1 setup >

BIT	Name	Init		Function								
DII	Name	Init		()			1				
D7	-	-			-				-			
D6	IG11(6)	0	IG11(6)	IG11(5)	IG11(4)	IG11(3)	IG11(2)	IG11(1)	IG11(0)	Current		
D5	IG11(5)	0	0	0	0	0	0	0	0	0		
D4	IG11(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IG11(3)	0							•	0.2mA step		
D2	IG11(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IG11(1)	0	1 1 1 1 1 1 1 25.4mA							25.4mA		
D0	IG11(0)	0	At RGBISETpin 120kΩ connection									

Adress 07h <G1 current2 setup >

BIT	Name	Init		Function								
DII	Name	IIIIL		()			1				
D7	-	-		-	-				-			
D6	IG12(6)	0	IG12(6)	IG12(5)	IG12(4)	IG12(3)	IG12(2)	IG12(1)	IG12(0)	Current		
D5	IG12(5)	0	0	0	0	0	0	0	0	0		
D4	IG12(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IG12(3)	0						•		0.2mA step		
D2	IG12(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IG12(1)	0	1 1 1 1 1 1 1 25.						25.4mA			
D0	IG12(0)	0	At RGBISETpin 120kΩ connection									

Adress 08h <G1 G1 Wave Pattern >

BIT	Name	Init			Fun	ction				
DII	Name	mint		0			1			
D7	-	-		-			-			
D6	-	-		-			-			
D5	-	-		-			-			
D4	-	-		-			-			
D 2		0	PG1(3)	PG1(2)	PG1(1)	PG1(0)	Wave			
D3	PG1(3)	0	0	0	0	0	Pattern 1			
			0	0	0	1	Pattern 2			
D2	PG1(2)	1	0	0	1	0	Pattern 3			
	,		•	•	•	•	-			
			•	•	•	•	•			
D1	PG1(1)	1	•	•	•	•	•			
			1	1	0	1	Pattern 14			
00	D0 PG1(0)	PG1(0)	PG1(0)	PG1(0)	PG1(0) 1		1	1	0	Pattern 15
50		1	1	1	1	1	Pattern 16			

Adress 09h <B1 current1setup >

BIT	Name	Init		Function								
DII	Name	IIIIL			0			1				
D7	-	-			-				-			
D6	IB11(6)	0	IB11(6)	IB11(5)	IB11(4)	IB11(3)	IB11(2)	IB11(1)	IB11(0)	Current		
D5	IB11(5)	0	0	0	0	0	0	0	0	0		
D4	IB11(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IB11(3)	0								0.2mA step		
D2	IB11(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IB11(1)	0							1	25.4mA		
D0	IB11(0)	0	At RGBISETpin 120kΩ connection									

Adress 0Ah <B1 current2setup >

BIT	Name	Init				Function						
DII	name	mm		()			1				
D7	-	-			-				-			
D6	IB12(6)	0	IB12(6)	IB12(5)	IB12(4)	IB12(3)	IB12(2)	IB12(1)	IB12(0)	Current		
D5	IB12(5)	0	0	0	0	0	0	0	0	0		
D4	IB12(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IB12(3)	0				•	•	•	•	0.2mA step		
D2	IB12(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IB12(1)	0	1 1 1 1 1 1 1 1 25.4mA						25.4mA			
D0	IB12(0)	0	At RGBISETpin 120kΩ connection									

Adress 0Bh <B1 Wave Pattern >

BIT	Name	Init			Fur	Inction			
DII	Name	mme		0			1		
D7	-	-		-		-			
D6	-	-		-			-		
D5	-	-		-			-		
D4	-	-		-			-		
D3	PB1(3)	0	PB1(3)	PB1(2)	PB1(1)	PB1(0)	Wave		
00			0	0	0	0	Pattern1		
			0	0	0	1	Pattern2		
D2	PB1(2)	1	0	0	1	0	Pattern3		
			•	•	•	•	•		
			•	•	•	•			
D1	PB1(1)	1	•	•	•	•			
			1	1	0	1	Pattern14		
Do		1	1	1	1	0	Pattern15		
D0	PB1(0)	PB1(0)	1	1	1	1	1	Pattern16	

Adress 0Ch <RGB2 time >

ВІТ	Name	Init			Function	
ЫТ	Name	mit		0		1
			SFRGB2(1)	SFRGB2(0)	Slope Down transition
D7	SFRGB2(1)	0	0		0	0
			0		1	Wave form cycle / 16
			1		0	Wave form cycle / 8
			1		1	Wave form cycle / 4
D6	SFRGB2(0)	0	not included.	-	ntrol, and the reaction estart to a slope er	on time of the analog section is nd.
			SRRGB2(1)	SRRGB2(0)	Slope up transition
D5	SRRGB2(1)	0	0		0	0
	0	· ·	0		1	Wave form cycle / 16
			1		0	Wave form cycle / 8
			1		1	Wave form cycle / 4
D4	SRRGB2(0)	0	included.	-	l, and the reaction t e start to a slope en	ime of the analog section is not d.
D3	-	-		-		-
			TRGB2(2)	TRGB2(1)	TRGB2(0)	Wave form cycle
D2	TRGB2(2)	0	0	0	0	0.131 s
			0	0	1	0.52 s
			0	1	0	1.05 s
D1	TRGB2(1)	0	0	1	1	2.10 s
			1	0	0	4.19 s
			1	0	1	8.39 s
D0	00 TRGB2(0)	2(0) 0	1 1		0	12.6 s
-	- (-)		1	1	1	16.8 s

Setting time is counted based on the frequency of OSC. The above-mentioned value is a value at the time of Typ (1MHz). When operating by the external clock, input frequency is a value at the time of Typ (250kHz)

Adress 0Dh <R2 current 1setup>

ріт	Name	Init		Function							
BIT	iname	IIIIL		()		1				
D7	-	-		-	-				-		
D6	IR21(6)	0	IR21(6)	IR21(5)	IR21(4)	IR21(3)	IR21(2)	IR21(1)	IR21(0)	Current	
D5	IR21(5)	0	0	0	0	0	0	0	0	0	
D4	IR21(4)	0	0	0	0	0	0	0	1	0.2mA	
D3	IR21(3)	0				•				0.2mA step	
D2	IR21(2)	0	1	1	1	1	1	1	0	25.2mA	
D1	IR21(1)	0	1 1 1 1 1 1 1 25.4mA							25.4mA	
D0	IR21(0)	0	At RGBISETpin 120kΩ connection								

Adress 0Eh <R2 current 2setup>

BIT	Name	Init		Function									
ЫТ	Name	ITIIL		()			1					
D7	-	-			-				-				
D6	IR22(6)	0	IR22(6)	IR22(5)	IR22(4)	IR22(3)	IR22(2)	IR22(1)	IR22(0)	Current			
D5	IR22(5)	0	0	0	0	0	0	0	0	0			
D4	IR22(4)	0	0	0	0	0	0	0	1	0.2mA			
D3	IR22(3)	0	· ·	•	•	•	•	•	•	0.2mA			
50	. ,	0	•	•	•	•	•	•	•	step			
D2	IR22(2)	0	1	1	1	1	1	1	0	25.2mA			
D1	IR22(1)	0	1 1 1 1 1 1 1 1 25.4mA							25.4mA			
D0	IR22(0)	0	At RGBISETpin 120kΩ connection										

Adress 0Fh <R2 Wave Pattern setup>

BIT	Name	Init			Fun	ction			
DII	Name	mint		0			1		
D7	-	-		-		-			
D6	-	-		-			-		
D5	-	-		-			-		
D4	-	-		-			-		
D3	00/2)	0	PR2(3)	PR2(2)	PR2(1)	PR2(0)	Wave		
05	PR2(3)	0	0	0	0	0	Pattern 1		
			0	0	0	1	Pattern 2		
D2	PR2(2)	1	0	0	1	0	Pattern 3		
			•	•	•	•			
			•	•	•	•			
D1	PR2(1)	1	•	•	•	•			
			1	1	0	1	Pattern 14		
DO	D0 PR2(0) 1		1	1	1	0	Pattern 15		
00			1	1	1	1	Pattern 16		

Adress 10h <G2 current 1setup>

ріт		Init		Function							
BIT	Name	Init		0				1			
D7	-	-		-	-				-		
D6	IG21(6)	0	IG21(6)	IG21(5)	IG21(4)	IG21(3)	IG21(2)	IG21(1)	IG21(0)	Current	
D5	IG21(5)	0	0	0	0	0	0	0	0	0	
D4	IG21(4)	0	0	0	0	0	0	0	1	0.2mA	
D3	IG21(3)	0								0.2mA step	
D2	IG21(2)	0	1	1	1	1	1	1	0	25.2mA	
D1	IG21(1)	0	1	1	1	1	1	1	1	25.4mA	
D0	IG21(0)	0	At RGBISE	At RGBISETpin 120kΩ connection							

Adress 11h <G2 current 2setup>

ріт	Nome	lun it		Function						
BIT	Name	Init		()		1			
D7	-	-		-	-				-	
D6	IG22(6)	0	IG22(6)	IG22(5)	IG22(4)	IG22(3)	IG22(2)	IG22(1)	IG22(0)	Current
D5	IG22(5)	0	0	0	0	0	0	0	0	0
D4	IG22(4)	0	0	0	0	0	0	0	1	0.2mA
D3	IG22(3)	0			•		•			0.2mA step
D2	IG22(2)	0	1	1	1	1	1	1	0	25.2mA
D1	IG22(1)	0	1	1	1	1	1	1	1	25.4mA
D0	IG22(0)	0	At RGBISE	At RGBISETpin 120kΩ connection						

Adress 12h <G2 Wave Pattern setup >

BIT	Name	Init			Fun	ction			
DII	Name	Init		0		1			
D7	-	-		-			-		
D6	-	-		-			-		
D5	-	-		-			-		
D4	-	-		-			-		
		0	PG2(3)	PG2(2)	PG2(1)	PG2(0)	Wave		
D3	PG2(3)		0	0	0	0	0	0	Pattern 1
			0	0	0	1	Pattern 2		
D2	PG2(2)	1	0	0	1	0	Pattern 3		
			•	•	•	•	•		
			•	•	•	•	-		
D1	PG2(1)	1	1	1	•	•	•	•	-
			1	1	0	1	Pattern 14		
D0	PG2(0)	PG2(0) 1		1	1	0	Pattern 15		
50			1	1	1	1	Pattern 16		

Adress 13h <B2 current 1setup>

BIT	Name	Init		Function								
DII	Name	ITIIL		()			1				
D7	-	-			-				-			
D6	IB21(6)	0	IB21(6)	IB21(5)	IB21(4)	IB21(3)	IB21(2)	IB21(1)	IB21(0)	Current		
D5	IB21(5)	0	0	0	0	0	0	0	0	0		
D4	IB21(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IB21(3)	0	·	•	•	•	•	•	•	0.2mA		
D 0		0	·	•	•	•	•	•	•	step		
D2	IB21(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IB21(1)	0	1	1	1	1	1	1	1	25.4mA		
D0	IB21(0)	0	At RGBISE	At RGBISETpin 120kΩ connection								

Adress 14h <B2 current 2setup>

ЫТ	Name	Init	Function								
BIT	Name	IIII		0				1			
D7	-	-		-					-		
D6	IB22(6)	0	IB22(6)	IB22(5)	IB22(4)	IB22(3)	IB22(2)	IB22(1)	IB22(0)	Current	
D5	IB22(5)	0	0	0	0	0	0	0	0	0	
D4	IB22(4)	0	0	0	0	0	0	0	1	0.2mA	
D3	IB22(3)	0								0.2mA step	
D2	IB22(2)	0	1	1	1	1	1	1	0	25.2mA	
D1	IB22(1)	0	1	1	1	1	1	1	1	25.4mA	
D0	IB22(0)	0	At RGBISE	At RGBISETpin 120kΩ connection							

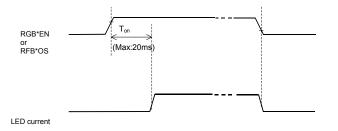
ЫТ	Name	Init		Function								
BIT	BIT Name I		0				1					
D7	-	-		-			-					
D6	-	-		-			-					
D5	-	-		-			-					
D4	-	-										
	D 0			PB2(3)	PB2(2)	PB2(1)	PB2(0)	Wave				
D3	PB2(3)	0	0	0	0	0	0	Pattern 1				
			0	0	0	1	Pattern 2					
D2	PB2(2)	1	0	0	1	0	Pattern 3					
	()		•	•	•	•	•					
			•	•	•	•	•					
D1	PB2(1)	1	•	•	•	•	•					
			1	1	0	1	Pattern 14					
D0	PB2(0)						1	1	1	1	0	Pattern 15
00		I	1	1	1	1	Pattern 16					

RGB LED Driver Operation Description

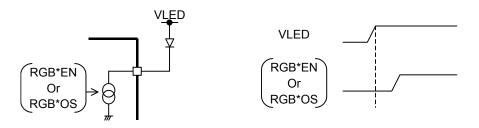
- Two drivers "RGB1 (R1LED, G1LED, B1LED)" and "RGB2 (R2LED, G2LED, B2LED)" are mounted.
- A slope function is incorporated to control drivers independently.
- Refer to RGB Waveform Setting for more information about output waveform setting.
- The LED current can be set via a resistance value (RISET) to be connected to the RGBISET terminal. The maximum current value can be derived from the following expression:

ILEDmax [A] = $3.048 / \text{RISET} [k\Omega] (Typ)$ However, this setting must be made so that the maximum current value can be less than or equal to 30.48mA. In addition, the RGBISET terminal has an overcurrent protection circuit to prevent the excessive LED current from flowing for low impedance to the ground.

- Note that the setting voltage shall be higher than or equal to a saturation voltage (0.2V) in the constant current circuit. When LED Vf is large, the LED destination shall be connected to another step-up circuit.



- The LED destination is fixed before on (RGB*EN=Hi or RGB*OS=Hi).



The synchronism of RGB1/RGB2

The period of RGB1 and RGB2 and start, stop timing can be set up independently. When synchronizes RGB1 and RGB2, You must start an internal counter at the same time under the state of resetting. (Internal Counter are prepared for each of RGB1 and RGB2, so You must reset both.)

<How to reset internal Counter> Inside Counter can be reset by carrying out one of following actions.

- Reset by hard reset (RSTB_IL). (RGB1, RGB2 is reset together.)
- Reset by soft reset. (RGB1, RGB2 is reset together.)
- It is written register of the current setup (I1 I2), the slope setup, the period setup and the pattern setup. Internal Counter of RGB1 is reset when it is written between Address=0Bh from 02h. Internal Counter of RGB2 is reset when it is written between Address=15h from 0Ch. Counter is reset as to overwriting the same value.

Note)

Internal Counter isn't reset if write RGB1EN =L and RGB2EN =L. (Address=01h). When it write RGB1EN=L (RGB2EN=L), inside Counter is held, and IC will operate from the held state at next restart.

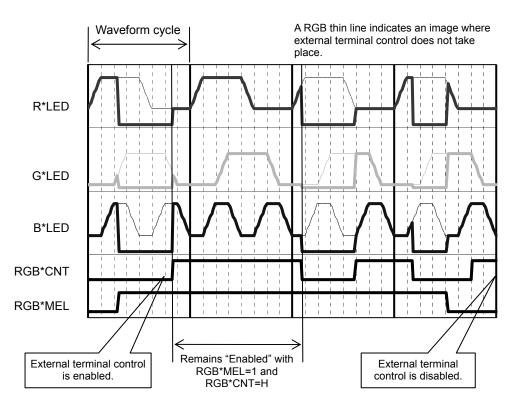
RGB Waveform Setting

Various kinds of RGB control can be implemented by designating waveform cycles, waveform patterns, current settings 1, 2 and rising/falling slope times.

To activate a RGB waveform, a continuous operation via RGB*EN or a single-shot operation via RGB*OS can be selected. In addition, when control via the external terminal RGB*CNT is enabled via RGB*MEL, the corresponding LED can be lit in synchronization with the external signal.

- 1. Waveform cycle
 - A single cycle time is set for a waveform pattern.
 - This setting can be made independently for RGB1 and RGB2.
- 2. Waveform pattern
 - A pattern in a waveform cycle is set.
 - · Sixteen types of waveform patterns can be set in units of waveform patterns.
 - For concrete waveform patterns, refer to the timing diagram shown on the next page.
- 3. Current settings 1 and 2 (I1, I2)
 - Two currents in a waveform pattern are set.
 - When the maximum current value is 25.4mA, it is possible to set the current ranging from 0 to 25.4mA with an increment of 0.2mA (128 steps).
 - The polarity of a waveform is determined by the greater-than/ less-than relationship in the current setting.
 - This setting can be made in units of terminals.
- 4. Rising/falling slope time
 - A current change time during switching between current settings 1 and 2 is set.
 - A time per step (0.2mA) is calculated based on a difference between the currents selected in current settings 1, 2 and a setting slope time.
 - For this reason, a time per step (0.2mA) is short when a difference between setting currents I1 and I2 is large. In contrast, it is long when a difference between setting currents I1 and I2 is small.
- Regardless of current settings 1 and 2, a rising slope time applies at current increase and a falling slope time applies at current decrease. For concrete waveform images, refer to the timing diagram shown on the next page.
 External terminal synchronization control

When control via the external terminal RGB*CNT is enabled via RGB*MEL, lighting is enabled if the input external signal goes "H." In contrast, it is disabled if the external input signal goes "L." In this way, synchronization with the external signal is enabled so that LED can be blinked in conjunction with a ringing tone (a melody signaling a ringtone).



		←			Wave	cycle			
•	ster data		1			12			
Wave pattern 1	(00h)	<u> </u> 1				12			
Wave pattern2	(01h)		1			l2	2		
Wave pattern 3	(02h)		11				12		
Wave pattern 4	(03h)		I	1			Ľ	2	
Wave pattern 5	(04h)			11				12	
Wave pattern 6	(05h)			l	1				12
Wave pattern 7	(06h)				l1				12
Wave pattern 8	(07h)				11				
Wave pattern 9	(08h)		1		2		l	1	
Wave pattern 10	(09h)			1			2		11
Wave pattern 11	(0Ah)	1	l l	2	l		l	2	1
Wave pattern 12	(0Bh)		1		2	I	1		12
Wave pattern 13	(0Ch)	1			2			11	
Wave pattern 14	(0Dh)		1		12	2			11
Wave pattern 15	(0Eh)		1			12	2		1
Wave pattern 16	(0Fh)	1	12	1	12	11	12	1	2
C) The imag Current 2(I2) pe uptransiti)	rent cha	nge of \		tern 11 own tra	nsition		
(Current 1(I1))	K.				V		

RGB wave setting timing diagram

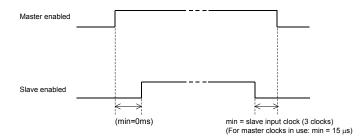
6. Clock I/O

A reference clock I/O function is mounted in this IC chip. When two IC chips are used to extend an illumination capability, clock supply to the other RGB LED driver can be accomplished for synchronization with this LSI chip. This setting can be made via the register.

Clock output can be made with CLKEN=1 and CLKMD=1.

1. 2									
	Reg	ister	CLKIO terminal state	Clock reception					
	CLKEN	CLKMD	CERIO terminal state						
	0	0/1 Input		Does not receive external clocks.					
	1	0	Input	Operates on external clocks.					
	I	1	Output	-					

When two BD2802GU drivers are used and the clock is shared by CLKIO: Because a sequence is already programmed within an IC chip for RGB falling, "Enable" shall be set to "OFF" and clock supply shall be continued for at least three clocks so that operations can be performed using external clocks.



Master: Chip using CLKIO as output Slave: Chip using CLKIO as input

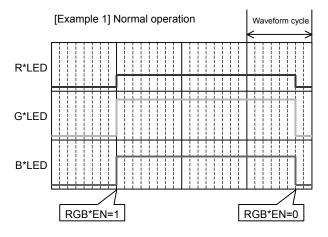
*Even in independent slave mode, its setting "Enable" shall be reset to "OFF" and then clock supply must be continued for 3 clocks or more.

Clock I/O switching shall be avoided during RGB operation. Enable: CLKEN, RGB1EN, RGB2EN, RGB1OS, RGB2OS

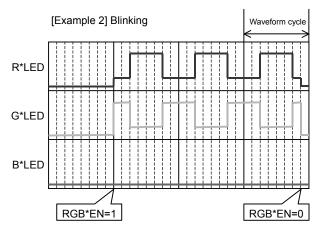
 Setting e 	example
-------------------------------	---------

0 1						
Master side \downarrow	(clock output side)	RGB waveform setting				
Slave side \downarrow	(clock input side)	RGB waveform setting				
Master side	Clock output setting					
	CLKEN=1, CLKMD=1	Performs clock output.				
\downarrow						
Slave side	Clock input setting					
	CLKEN=1, CLKMD=0	Allows clock reception.				
\downarrow						
Master side	RGB lighting					
\downarrow						
\downarrow	This duration shall be short as much as possible.					
\downarrow						
Slave side	RGB lighting					

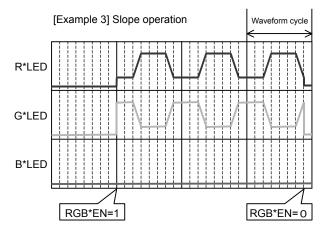
7. RGB waveform setting examples



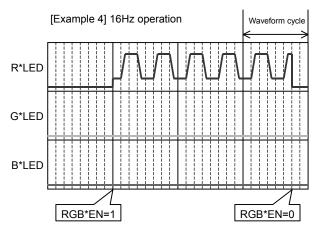
Selecting a waveform pattern 8 causes a continuous normal operation to take place through the setting current 1.



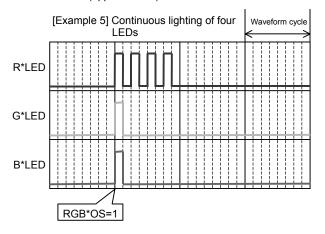
Setting a rising/falling slope time to "0" causes blinking to take place. Phase switching takes place via the setting currents of R and G.



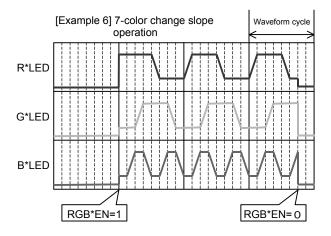
When a rising/falling slope time is longer than the setting made in example 2, a continuous color change is made by slope operation.



Combining the settings of a waveform pattern 11 and a waveform cycle 131ms causes blinking at a rate of 15.3Hz (approx. 16Hz).

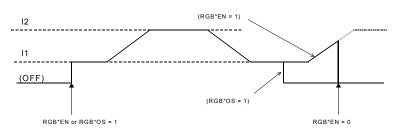


This example shows that lighting occurs continuously in the order of white, red, red and red. To achieve this, waveform patterns 16, 1 and RGB*OS single cycle operation need to be combined.

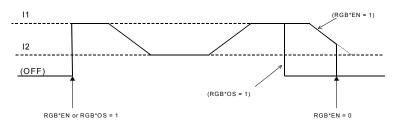


R, G and B waveform patterns are set in a way that any of R, G and B changes constantly.

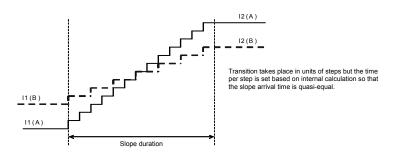
- 8. RGB slope waveforms
 - Example of waveform at activation Current setting: I1 < I2







- Current difference in each channel (example)



9. Setting change in slope duration

A slope operation is performed by an internal sequencer.

When an attempt is made to change the setting in a slope duration, the active slope operation is reset and a newly set slope operation is restarted.

In this case, however, LED lighting stops for a maximum of 16.4ms (OSC frequency=typ) for synchronization with the internal clock until the operation is restarted.

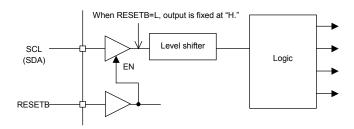
Description of other operations

- 1. Reset
 - There are two types of reset: software reset and hardware reset.
 - (1) Software reset
 - Setting the register (SFTRST) to "1" causes all the registers to be initialized.
 - The registers subject to software reset automatically return to zero (Auto Return 0).
 - (2) Hardware reset
 - Changing the RESETB terminal setting from "H" to "L" causes a state subject to hardware reset.
 - Attempting hardware reset causes the states of all registers and output terminals to be initialized to their initial values, so that address reception is entirely stopped.
 - Attempting reset in the hardware reset state causes the RESETB terminal state to change from "L" to "H" and vice versa.
 - The RESETB terminal is provided with a filter circuit and a duration of 5µs or less with the terminal set to "L" is not recognized as hardware reset.
 - (3) Reset sequence
 - When hardware reset is attempted during software reset, software reset is already cleared when hardware reset is cleared (because the software reset initial value is 0).
- 2. Thermal shutdown
 - The thermal shutdown is effective for LED and OSC portions.
 - The thermal shutdown function is activated when the detected temperature is approx. 195°C.

The detected temperature has a hysteresis and the detection cancel temperature is approx. 175°C (reference value in design).

3. I/O portion

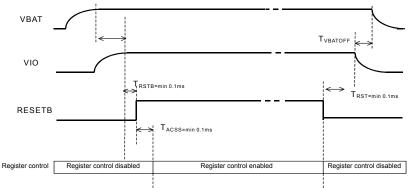
While the RESETB terminal is in "L" state, no input signal is propagated to the IC logic portion because SDA and SCL input buffer operations are all stopped.



Special care should be taken because a current path may be formed via a terminal protection diode, depending on an I/O power-on sequence or an input level.

4. Power on/off sequence

Voltage shall be applied as follows at driver activation. When a delay element is connected to a VIO voltage source and a reset cancel signal is input to the RESETB terminal, special care should be taken to the rising time of VIO voltage to delay the RESETB signal without fail.

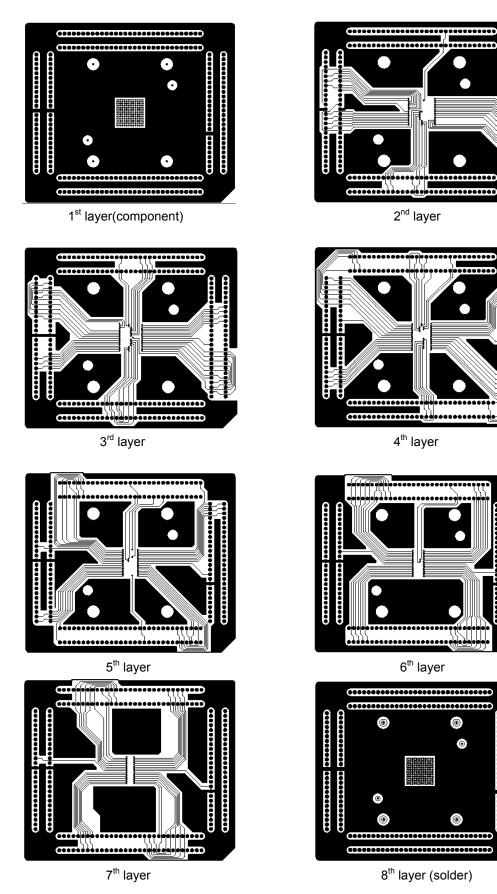


5. Terminating the unused terminals

Be sure to set the test terminals and unused terminals as summarized in the following table. In addition, refer to the preceding equivalent circuit and terminate the above terminals in a way that no problem occurs during actual use.

T1, T2, T3, T4	Test input terminals. Short-circuit these terminals to GND.						
LED terminals not to be used	Short-circuit these terminals to GND.						
LED terminals not to be used	In this case, don't set the registers related to LEDs not to be used.						
RGB1CNT, RGB2CNTShort-circuit these terminals to GND.(Built-in pull-down resistance)							
CLKIO	Short-circuit this terminal to GND.(Built-in pull-down resistance)						
ADDSEL	Be sure to short-circuit this terminal to VBAT or GND.						

●PCB pattern of the Power dissipation measuring board



Notes for Use

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Power supply and ground line

Design PCB pattern to provide low impedance for the wiring between the power supply and the ground lines. Pay attention to the interference by common impedance of layout pattern when there are plural power supplies and ground lines. Especially, when there are ground pattern for small signal and ground pattern for large current included the external circuits, please separate each ground pattern. Furthermore, for all power supply pins to ICs, mount a capacitor between the power supply and the ground pin. At the same time, in order to use a capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(3) Ground voltage

Make setting of the potential of the ground pin so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no pins are at a potential lower than the ground voltage including an actual electric transient.

(4) Short circuit between pins and erroneous mounting In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between pins or between the pin and the power supply or the ground pin, the ICs can break down.

(5) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(6) Input pins

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input pin. Therefore, pay thorough attention not to handle the input pins, such as to apply to the input pins a voltage lower than the ground respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input pins when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input pins a voltage lower than the govern than the power supply voltage or within the guaranteed value of electrical characteristics.

(7) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(8) Thermal shutdown circuit (TSD)

This LSI builds in a thermal shutdown (TSD) circuit. When junction temperatures become detection temperature or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.

(9) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use.

(10) About the pin for the test, the un-use pin

Prevent a problem from being in the pin for the test and the un-use pin under the state of actual use. Please refer to a function manual and an application notebook. And, as for the pin that doesn't specially have an explanation, ask our company person in charge.

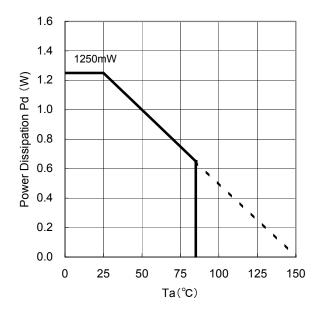
(11) About the rush current

Because the rush current flows momentarily for internal logic instability caused by a power-on sequence or delay, special care should be taken to the power supply coupling capacity, power supply, ground pattern wiring width and wiring.

(12) About descriptions given in this document

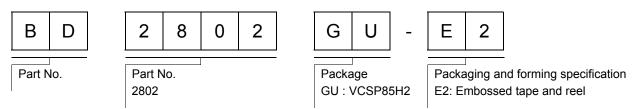
Though the function description and application node are design documents prepared for application design, we don't take liability for descriptions given in these documents. Be sure to decide applications after thoroughly investigating and evaluating the external devices as well as this BS2802GU LED driver.

Power Dissipation (On the ROHM's standard board)

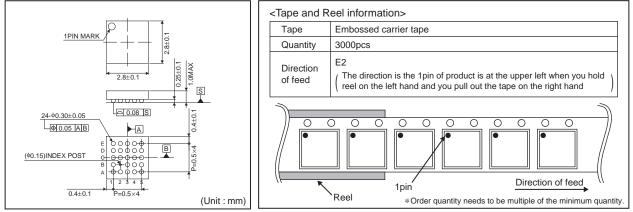


Information of the ROHM's standard board Material : glass-epoxy Size : 50mm×58mm×1.75mm (8Layer) Pattern of the board: Refer to it that goes later.

Ordering part number



VCSP85H2 (BD2802GU)



	Notes
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